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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
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10/776,487

02/10/2004

Ho-Yuan Yu

65860-5002-US

3256

24341

7590

11/13/2006

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EXAMINER

NGUYEN, KHIEM D

ART UNIT

PAPER NUMBER

2823

DATE MAILED: 11/13/2006

Please find below and/or attached an Office communication concerning this application or proceeding.

A

Office Action Summary	Application No. 10/776,487	Applicant(s) YU, HO-YUAN	
	Examiner Khiem D. Nguyen	Art Unit 2823	

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

- 1) ☒ Responsive to communication(s) filed on 12 September 2006.
- 2a) ☐ This action is FINAL. 2b) ☒ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

- 4) ☒ Claim(s) 15-34 is/are pending in the application.
- 4a) Of the above claim(s) _____ is/are withdrawn from consideration.
- 5) ☒ Claim(s) 15-20 is/are allowed.
- 6) ☒ Claim(s) 21-24 and 26-34 is/are rejected.
- 7) ☒ Claim(s) 25 is/are objected to.
- 8) ☐ Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☒ The drawing(s) filed on 10 February 2004 is/are: a) ☒ accepted or b) ☐ objected to by the Examiner.
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

- 12) ☒ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☒ All b) ☐ Some * c) ☐ None of:
1. ☐ Certified copies of the priority documents have been received.
 2. ☐ Certified copies of the priority documents have been received in Application No. _____.
 3. ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

* See the attached detailed Office action for a list of the certified copies not received.

HSIEN-MING LEE
PRIMARY EXAMINER

11/9/06

Attachment(s)

- | | |
|--|---|
| 1) <input checked="" type="checkbox"/> Notice of References Cited (PTO-892) | 4) <input type="checkbox"/> Interview Summary (PTO-413)
Paper No(s)/Mail Date. _____ |
| 2) <input type="checkbox"/> Notice of Draftsperson's Patent Drawing Review (PTO-948) | 5) <input type="checkbox"/> Notice of Informal Patent Application |
| 3) <input type="checkbox"/> Information Disclosure Statement(s) (PTO/SB/08)
Paper No(s)/Mail Date _____ | 6) <input type="checkbox"/> Other: _____ |

DETAILED ACTION

Continued Examination Under 37 CFR 1.114

1. A request for continued examination under 37 CFR 1.114, including the fee set forth in 37 CFR 1.17(e), was filed in this application after final rejection. Since this application is eligible for continued examination under 37 CFR 1.114, and the fee set forth in 37 CFR 1.17(e) has been timely paid, the finality of the previous Office action has been withdrawn pursuant to 37 CFR 1.114. Applicant's submission filed on September 12th, 2006 has been entered. A new rejection is made as set forth in this Office Action. Claims (15-34) are pending in the application.

Claim Rejections - 35 USC § 102

2. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

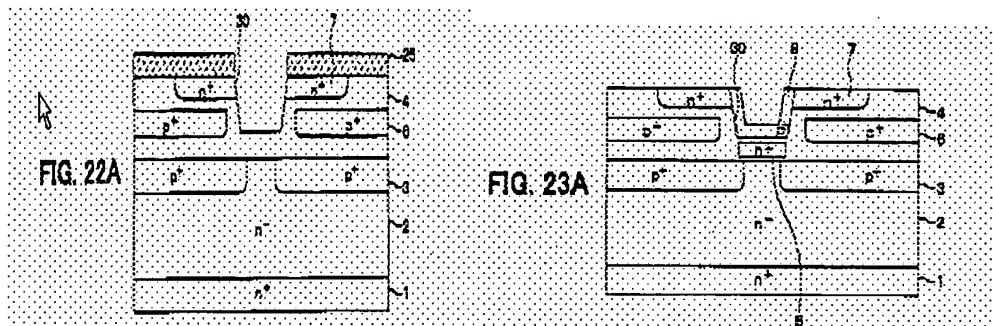
A person shall be entitled to a patent unless –

(e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.

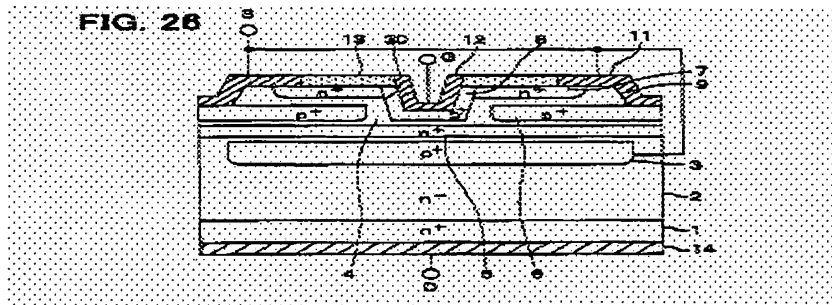
3. Claims 21-24 and 26-34 are rejected under 35 U.S.C. 102(e) as being anticipated by Kumar et al. (U.S. Pub. 2002/0167011).

In re claim 21, **Kumar** discloses a method for fabricating a dual gate structure for a field effect transistor (FET), the method comprising: in sequence, etching a gate trench 30 in a surface of a semiconductor substrate 1 (page 7, paragraph [0156] and FIG. 22A);

forming a first gate region 8 at the bottom of the gate trench 30 (page 7, paragraph [0160]); implanting a buffer region 5 beneath the first gate region 8 (page 7, paragraph [0158] and FIGS. 22 A and 23A); and



implanting a second gate region 3 beneath the buffer region 5, wherein the second gate region 3 is formed entirely beneath the first gate region 8 (page 7, paragraph [0164] and FIG. 26).



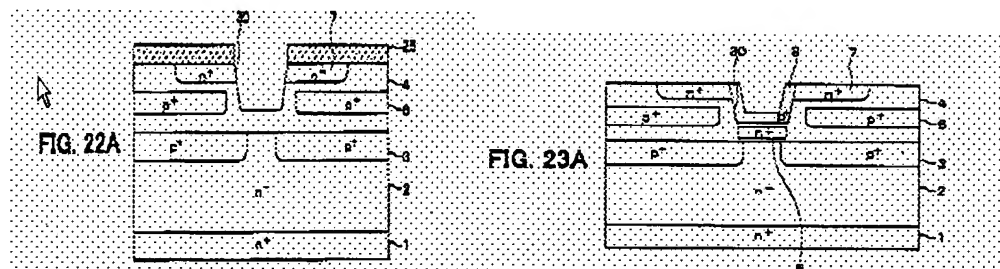
In re claim 22, as applied to claim 21 above, **Kumar** discloses all claimed limitations including the limitation wherein the method further comprising forming a sidewall spacer to establish a width of the first gate region 8 (FIG. 23A).

In re claim 23, as applied to claim 21 above, **Kumar** discloses all claimed limitations including the limitation wherein the method further comprising forming a sidewall spacer to establish a width of the buffer region 5 (FIG. 23B).

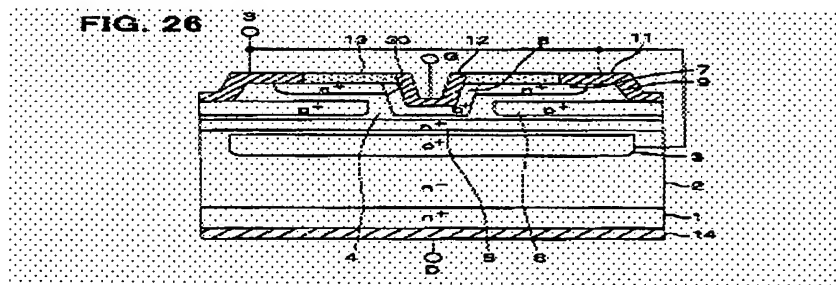
In re claim 24, as applied to claim 21 above, **Kumar** discloses all claimed limitations including the limitation wherein the method further comprising forming a sidewall spacer to establish a width of the second gate region 3 (FIG. 26).

In re claim 26, **Kumar** discloses a method for fabricating a dual gate structure for a field effect transistor (FET), the method comprising: etching a gate trench 30 in a surface of a semiconductor substrate 1 (page 7, paragraph [0156] and FIG. 22A);

forming a first gate region 8 at the bottom of the gate trench 30 (page 7, paragraph [0160]); after forming the first gate region, implanting a buffer region 5 beneath the first gate region 8 (page 7, paragraph [0158] and FIGS. 22A and 23A); and



implanting a second gate region 3 beneath the buffer region 5, wherein the second gate region 3 is formed entirely beneath the first gate region 8 (page 7, paragraph [0164] and FIG. 26).



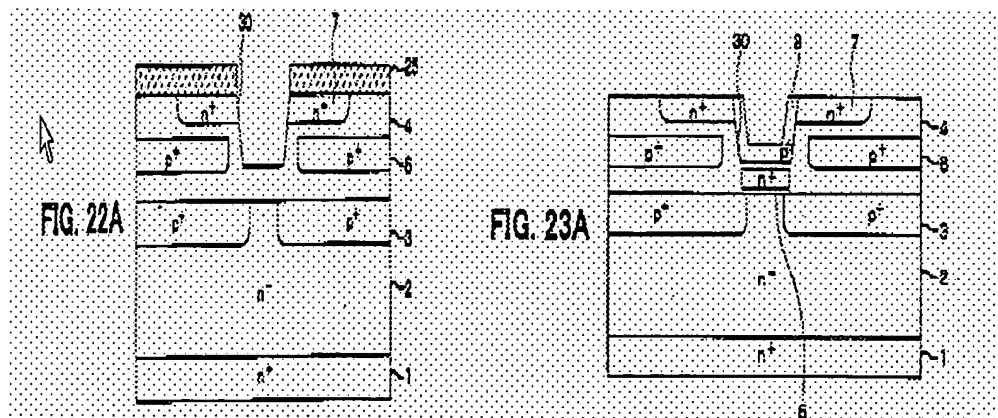
In re claim 27, as applied to claim 26 above, **Kumar** discloses all claimed limitations including the limitation wherein the method further comprising forming a sidewall spacer to establish a width of the first gate region 8 (FIG. 23A).

In re claim 28, as applied to claim 26 above, **Kumar** discloses all claimed limitations including the limitation wherein the method further comprising forming a sidewall spacer to establish a width of the buffer region 5 (FIG. 23B).

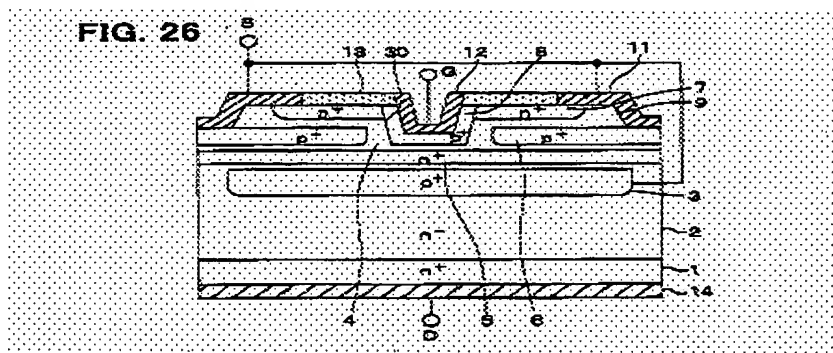
In re claim 29, as applied to claim 26 above, **Kumar** discloses all claimed limitations including the limitation wherein the method further comprising forming a sidewall spacer to establish a width of the second gate region 3 (FIG. 26).

In re claim 30, **Kumar** discloses a method for fabricating a dual gate structure for a field effect transistor the method comprising: etching a gate trench 30 in a surface of a semiconductor substrate 1 (page 7, paragraph [0156] and FIG. 22A);

forming a first gate region 8 at the bottom of the gate trench 30 (page 7, paragraph [0160]); implanting a buffer region 5 beneath the first gate region 8 (page 7, paragraph [0158] and FIG. 22A and 23A); and



after implanting the buffer region 5, implanting a second gate region 3 beneath the buffer region, wherein said second gate region 3 is formed entirely beneath said first gate region 8 (page 7, paragraph [0164] and FIG. 26).



In re claim 31, as applied to claim 30 above, Kumar discloses all claimed limitations including the limitation wherein the method further comprising forming a sidewall spacer to establish a width of the first gate region 8 (FIG. 23A).

In re claim 32, as applied to claim 30 above, Kumar discloses all claimed limitations including the limitation wherein the method further comprising forming a sidewall spacer to establish a width of the buffer region 5 (FIG. 23B).

In re claim 33, as applied to claim 30 above, Kumar discloses all claimed limitations including the limitation wherein the method further comprising forming a sidewall spacer to establish a width of the second gate region 3 (FIG. 26).

In re claim 34, as applied to claim 30 above, Kumar discloses all claimed limitations including the limitation wherein the method further comprising forming a first sidewall spacer to establish a width of the buffer region 5, and forming a second sidewall spacer to establish a width of the second gate region 3, wherein the second sidewall spacer is thicker than the first sidewall spacer (FIG. 26).

Allowable Subject Matter

4. Claims 15-20 are allowed over prior art of record.
5. Claim 25 is objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims.

Reasons For Allowance

6. The following is an examiner's statement of reasons for allowance:

After further search and consideration of Applicant's response filed on September 12th, 2006 (see Applicant's argument in Page 6 of the September 12th, response), it is determined that the prior art of record neither anticipates nor renders obvious the claimed subject matter of the instant application as a whole taken alone or in combination, in particular, prior art of record does not teach "implanting a second gate region beneath the buffer region, wherein the second gate region is formed entirely beneath the first gate region, and wherein, at a conclusion of implanting the second gate region, the second gate region is continuous in the lateral direction and is narrower than the first gate region", as recited in the currently amended independent claim 15.

Claims 16-20 also allowed as being directly or indirectly dependent of the allowed independent base claims.

Response to Applicant's Amendment and argument

7. Applicant's arguments with respect to claims 21-34 have been considered but are moot in view of the new ground(s) of rejection.

Conclusion

8. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Khiem D. Nguyen whose telephone number is (571) 272-1865. The examiner can normally be reached on Monday-Friday (8:30 AM - 5:30 PM).

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Matthew S. Smith can be reached on (571) 272-1907. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

K.N.
November 09, 2006

HSIEN-MING LEE
PRIMARY EXAMINER

11/9/06